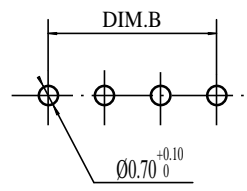
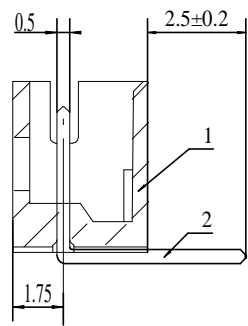
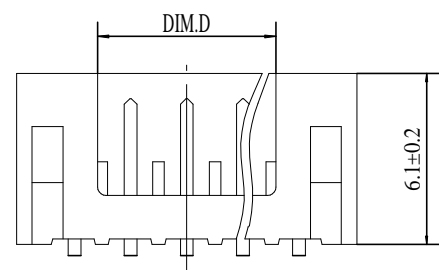
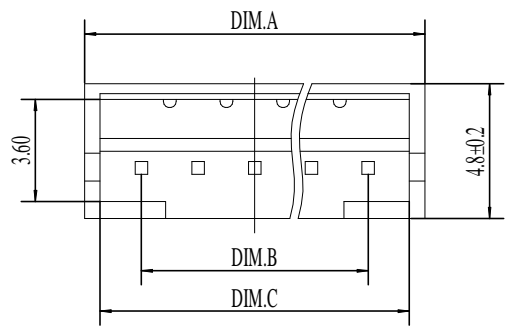


| REV. | EC# | DESCRIPTION | DATE | DRAWN | CHECK | APPROVED |
|------|-----|-------------|-----------|-------|-------|----------|
| 1.00 | | 初版发行 | 2020-8-28 | 瞿寿坤 | 胡海萍 | 胡海萍 |
| | | | | | | |

| NUMBER OF PINS | DIM.A | DIM.B | DIM.C | DIM.D |
|----------------|-------|-------|-------|-------|
| 15P | 32.0 | 28.0 | 30.9 | 26.8 |
| 14P | 30.0 | 26.0 | 28.9 | 24.8 |
| 13P | 28.0 | 24.0 | 26.9 | 22.8 |
| 12P | 26.0 | 22.0 | 24.9 | 20.8 |
| 11P | 24.0 | 20.0 | 22.9 | 18.8 |
| 10P | 22.0 | 18.0 | 20.9 | 16.8 |
| 9P | 20.0 | 16.0 | 18.9 | 14.8 |
| 8P | 18.0 | 14.0 | 16.9 | 12.8 |
| 7P | 16.0 | 12.0 | 14.9 | 10.8 |
| 6P | 14.0 | 10.0 | 12.9 | 8.8 |
| 5P | 12.0 | 8.0 | 10.9 | 6.8 |
| 4P | 10.0 | 6.0 | 8.9 | 4.8 |
| 3P | 8.0 | 4.0 | 6.9 | 2.8 |
| 2P | 6.0 | 2.0 | 4.9 | 0.8 |



PCB LAYOUT

| GENERAL TOLERANCES | | | |
|--------------------|-------|--------|--------|
| DIM | TOL | DIM | DEG |
| X | | X° | ±3.00° |
| X.X | ±0.35 | X.X° | ±2.00° |
| X.XX | ±0.25 | X.XX° | ±1.00° |
| X.XXX | ±0.15 | X.XXX° | |

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25℃~85℃
 额定电压: 250V AC/DC
 额定电流: 1A
 绝缘电阻: >1000MΩ
 耐压: 800V AC/minute

| 2 | PIN | n PCS | 材质:黄铜,电镀:镀亮锡60u"MIN |
|-----|---------|-------|---------------------|
| 1 | Housing | 1 PCS | 材质:PA66 颜色:本色 |
| NO. | NAME | QTY | DESCRIPTION |

深圳市虹成电子有限公司

| | | | | | |
|------------------|-----|-----------|-----------------------------|------------|------------|
| DRAW: | 瞿寿坤 | 2020-8-28 | TITLE: WAFER PH2.0WA 卧式 DIP | DRAW NAME: | HCZZ0295-6 |
| DESIGN: | 瞿寿坤 | 2020-8-28 | SERIES: 1501 SERIES | | |
| CHECK: | 胡海萍 | 2020-8-28 | P/N: | DRAW NO. | |
| APPROVED | 胡海萍 | 2020-8-28 | REV. 1.00 | SCALE N/A | UNIT: mm |
| CUSTOMER DRAWING | | | | | SHEET: 1/1 |

